

## Japan TC Chapter of Physical Interfaces & Carriers Global Technical Committee Meeting Summary and Minutes

Japan Standards Spring 2014 Meetings  
Friday, April 18, 2014, 1:30 p.m. – 5 p.m.  
SEMI Japan office, Tokyo, Japan

### Next Committee Meeting

Friday, September 12, 2014, 1:30 p.m. – 5 p.m. <Japan Standard Time>  
Japan Standards Fall 2014 Meetings  
SEMI Japan office, Tokyo, Japan

### Committee Announcements (optional)

None

### Table 1 Meeting Attendees

**Co-Chairs:** Tsuyoshi Nagashima (Miraial), Tsutomu Okabe (TDK), Kenji Yamagata (Daifuku)

**SEMI Staff:** Chie Yanagisawa (SEMI Japan)

**Attendee:** 12 + **SEMI:** 1

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Acteon	Komatsu	Shoji	Murata Machinery	Itou	Yasuhisa
Daifuku	Yamagata	Kenji	Shimizu Consulting	Shimizu	Yasuhiro
Dainichi Shoji	Ohyama	Koji	Sinfonia Technology	Otani	Mikio
Hitachi Kokusai Electric	Matsuda	Mitsuhiro	SUMCO	Nakai	Tetsuya
Kumai Consulting	Kumai	Sadao	TDK	Okabe	Tsutomu
Miraial	Nagashima	Tsuyoshi	Tokyo Electron	Mashiro	Supika

\* alphabetical order by company name

### Table 2 Leadership Changes

None

### Table 3 Ballot Results (or move to Section 4, Ballot Review)

**Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

**Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
5626	Line Item Revisions to SEMI E154-0713, <i>Mechanical Interface Specification for 450 mm Load Port</i> AND to SEMI E166-0513, <i>Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard for addition of EFEM Pocket</i>	<b>Passed</b> as balloted with editorial changes

### Table 4 Authorized Ballots (or move to Section 7, New Business)

None

### Table 5 Authorized Activities (or move to Section 7, New Business)

None

**Table 6 New Action Items (or move to Section 8, Action Item Review)**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
140418-1	SEMI Staff	To convey the decision that no workshop for STEP/450mm Wafers will be scheduled at SEMICON Japan 2014, but Shoji Komatsu (Acteon) would give a presentation for the Overview of 450mm Wafer Standards at TechStage to the Japan Silicon Wafer TC Chapter and the Japan Packaging TC Chapter. → CLOSED.

**Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
130904-1	Shoji Komatsu (Acteon)	For the approved charter of the Japan PIC Committee, Shoji Komatsu and Larry Hartsough review the editorial changes indicated in discussion during the Japan PIC Committee meeting on September 4, 2013. → CLOSED.
131206-1	SEMI Staff	Since a check box for Revision to an existing Auxiliary Information is missing in the SNARF form, Staff will input this issue to the Regulation Sub-Committee. → CLOSED. The item has been raised as one of the issues to the Regulation Subcommittee.

## 1 Welcome, Reminders, and Introductions

Tsuyoshi Nagashima (Mirial), co-chair, called the meeting to order at 1:30 p.m. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

## 2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

**Motion:** Approve the previous meeting minutes with correction of the company name of Hidetoshi Sato to “Hitachi High-Technologies”

**By / 2<sup>nd</sup>:** Mitsuhiro Matsuda (Hitachi Kokusai Electric) / Kenji Yamagata (DAIFUKU)

**Discussion:** None

**Vote:** 11 in favor and 0 opposed. **Motion passed.**

**Attachment:** [01, JA PIC Minutes\\_131206\\_Final](#)

## 3 Liaison Reports

### 3.1 Europe Equipment Automation Committee

Chie Yanagisawa (SEMI Japan) reported that there was no update for Europe Equipment Automation Committee.

### 3.2 North America PI&C Committee

Tsuyoshi Nagashima (Mirial) reported for the North America PI&C TC Chapter as attached. Of note:

- Leadership
- Organization Chart
- Meeting Information
- Ballot Results
- New Activities

- Current/Upcoming Ballots
- Task Force Reports
- Next Meeting Schedule

**Attachment:** [02, NA PIC Report April 2014 MT](#)

### 3.3 SEMI Staff Report

Chie Yanagisawa (SEMI Japan) gave the SEMI Staff Report. Of note:

- Global SEMI Events
- Global Standards Meetings Schedule
- Ballot Critical Dates
- Publication Update
- Contact Information

**Attachment:** [03, SEMI Staff Report 2014 Apr.\\_R0.3](#)

## 4 Ballot Review

4.1 Document 5626: Line Item Revisions to SEMI E154-0713, Mechanical Interface Specification for 450 mm Load Port AND to SEMI E166-0513, Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard for addition of EFEM Pocket

The details of ballot review are found in the attachment of “5626\_A&R”.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
5626	Line Item Revisions to SEMI E154-0713, <i>Mechanical Interface Specification for 450 mm Load Port AND to SEMI E166-0513, Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard for addition of EFEM Pocket</i>	<b>Passed</b> as balloted with editorial changes

**Attachment:** [04, 5626\\_A&R](#)

## 5 Subcommittee & Task Force Reports

### 5.1 Global PIC Standards Maintenance Task Force

Shoji Komatsu (Acteon) reported that there has been no activity.

### 5.2 International 450 mm Physical Interfaces & Carriers Task Force

Shoji Komatsu (Acteon) referred to International Process Module Physical Interface (IPPI) Task Force report at the following section.

### 5.3 International Process Module Physical Interface (IPPI) Task Force

Supika Mashiro (Tokyo Electron) reported for International Process Module Physical Interface (IPPI) Task Force. This report contained information on the following items.

- Ballot review Doc. 5626 at the North America Standards Spring 2014 Meetings
- 450 mm AUX023 update
- New Business: Planning survey for issues of 450 mm FOUP/MAC/LP related SEMI Standards

**Attachment:** [05, 450mm IPIC-IPPI TF meeting Minutes rev0-20140418](#)

### 5.4 Int'l Reticle SMIF Pod & Load Port Interoperability Task Force

Koji Oyama (Dainichi Shoji) reported that there has been no activity.

## 5.5 450 mm AMHS Task Force

Kenji Yamagata (DAIFUKU) reported for 450 mm AMHS Task Force. This report contained information on the following items.

- Working on the development of revised E156
  - Ballot to be casted by end of this year.
- Standardization on signal tower for AMHS is on hold.

**Attachment:** [06, 20140418JA 450mm AMHS TF Report R0.0](#)

## 5.6 Fiducial Mark Interoperability Task Force

Mitsuhiko Matsuda (Hitachi Kokusai Electric) reported for Fiducial Mark Interoperability Task Force. This report contained information on the following items.

- Shared and Discussed Document Draft #5604
- To be submitted feedback from TF members to “International Polished Wafer TF”
- T7 Revision: Traceability related
- Positioning after Back Gridding: Assembly and Packaging related
- Reading Condition Report: I&C related

For its information, Tetsuya Nakai (SUMCO) also reported for Fiducial Mark Interoperability Task Force about the revision to SNARF #5604 (Revision to SEMI M1). The detailed information is found in the attached 08 file.

**Attachment:** [07, 20140416FMI-TF-Report\\_r0](#), [08, M1 rev for 450mm NF\\_140408](#)

## 5.7 Int'l 450mm Shipping Box Task Force and JA Shipping Box Task Force

Yasuhiro Shimizu (Shimizu Consultant) reported for Int'l 450mm Shipping Box Task Force and JA Shipping Box Task Force. This report contained information on the following items.

- 450 mm Wafer Shipping System
  - Development for a new standard: Specification for 450 mm Wafer Shipping System
  - Rework of Doc.5069
  - Ballot Doc. 5069A for Cycle 2, 2014

**Attachment:** [09, Shipping Box TF Report](#)

## 6 Old Business

None

## 7 New Business

7.1 Discussion on Schedule of Standards meetings and program for STEP/450mm Wafers in conjunction with SEMICON Japan 2014 in December

Chie Yanagisawa (SEMI Japan) addressed the committee on this topic 100 minutes for presentation for All the Standards Committees at TechStage of SEMICON Japan 2014. The committee discussed and decided that no workshop for STEP/450mm Wafers will be scheduled at SEMICON Japan 2014, but Shoji Komatsu (Acteon) would give a presentation for the Overview of 450mm Wafer Standards at TechStage.

Chie Yanagisawa commented that the information for Preparation would be provided to Shoji Komatsu and the co-chairs of Japan PI&C Chapter.

**Action Item:** Chie Yanagisawa (SEMI Japan) to convey the decision that no workshop for STEP/450mm Wafers will be scheduled at SEMICON Japan 2014, but Shoji Komatsu (Acteon) would give a presentation for the

Overview of 450mm Wafer Standards at TechStage to the Japan Silicon Wafer TC Chapter and the Japan Packaging TC Chapter.

## **8 Action Item Review**

### *8.1 Open Action Items*

None

### *8.2 New Action Items*

Chie Yanagisawa (SEMI Japan) reviewed the new action item. This can be found in the New Action Items table at the beginning of these minutes.

## **9 Next Meeting and Adjournment**

The next meeting of the Japan TC Chapter of PIC Global Technical Committee is scheduled for Friday, September 12 at Japan Standards Fall 2014 Meetings at SEMI Japan office in Tokyo.

Respectfully submitted by:  
 Chie Yanagisawa  
 Senior Standard Coordinator  
 SEMI Japan  
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 Email: cyanagisawa@semi.org

Minutes approved by:

Tsuyoshi Nagashima (Miraial), Co-chair	September 12, 2014
Tsutomu Okabe (TDK), Co-chair	September 12, 2014
Kenji Yamagata (DAIFUKU), Co-chair	September 12, 2014

**Table 8 Index of Available Attachments #1**

#	<i>Title</i>	#	<i>Title</i>
01	JA PIC Minutes_131206_Final	06	20140418JA 450mm AMHS TF Report R0.0
02	NA PIC Report April 2014 MT	07	20140416FMI-TF-Report_r0
03	SEMI Staff Report 2014 Apr._R0.3	08	M1 rev for 450mm NF_140408
04	5626_A&R	09	Shipping Box TF Report
05	450mm IPIC-IPPI TF meeting Minutes rev0-20140418		

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.